

76mm (3.0INCH) SINGLE DIGIT DISPLAY

Part Number: SA30-21CGKWA Green

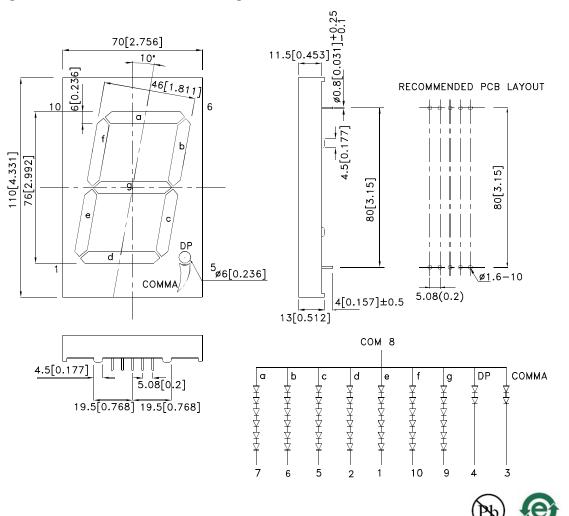
Features

- 3.0 inch digit height.
- Low current operation.
- Excellent character appearance.
- Easy mounting on P.C. boards or sockets.
- · Categorized for luminous intensity.
- Mechanically rugged.
- Standard : gray face, white segment.
- RoHS compliant.

Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram



Notes

1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.

2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 SPEC NO: DSAM9749
 REV NO: V.1A
 DATE: APR/23/2013
 PAGE: 1 OF 7

 APPROVED: WYNEC
 CHECKED: Joe Lee
 DRAWN: F.Cui
 ERP: 1301003374

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [1] @ 10mA		Description
1 2.11.01			Min.	Тур.	
SA30-21CGKWA	Green (AlGalnP)	White Diffused	88	170	Common Anode , Rt.Hand Decimal.
			*21	*50	

Notes:

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	574		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	20		nm	IF=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage (DP and Comma)	Green	12.6 (4.2)	15.0 (5.0)	V	I==20mA
lR	Reverse Current (Per Chip)	Green		10 (10)	uA	V _R =5V (V _R =5V)

Notes:

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units		
Power dissipation (DP and Comma)	450 (150)	mW		
DC Forward Current (DP and Comma)	30 (30)	mA		
Peak Forward Current [1] (DP and Comma)	150 (150)	mA		
Reverse Voltage (Per Chip)	5 (5)	٧		
Operating / Storage Temperature	-40°C To +85°C			
Lead Solder Temperature[2]	ure[2] 260°C For 3-5 Seconds			

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

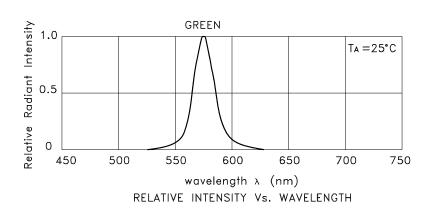
SPEC NO: DSAM9749 **REV NO: V.1A** DATE: APR/23/2013 PAGE: 2 OF 7 APPROVED: WYNEC **CHECKED:** Joe Lee DRAWN: F.Cui ERP: 1301003374

^{1.} Luminous intensity/ luminous Flux: +/-15%.

* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

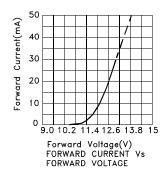
^{1.}Wavelength: +/-1nm.

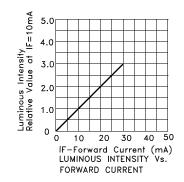
Forward Voltage: +/-0.1V.
 Wavelength value is traceable to the CIE127-2007 compliant national standards.

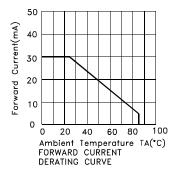


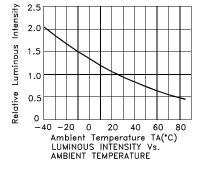
Green

SA30-21CGKWA

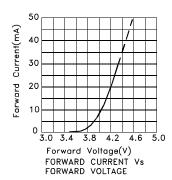


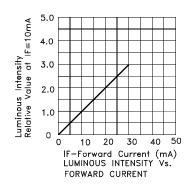


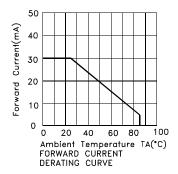


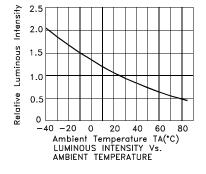


SPEC NO: DSAM9749 APPROVED: WYNEC REV NO: V.1A CHECKED: Joe Lee DATE: APR/23/2013 DRAWN: F.Cui PAGE: 3 OF 7 ERP: 1301003374

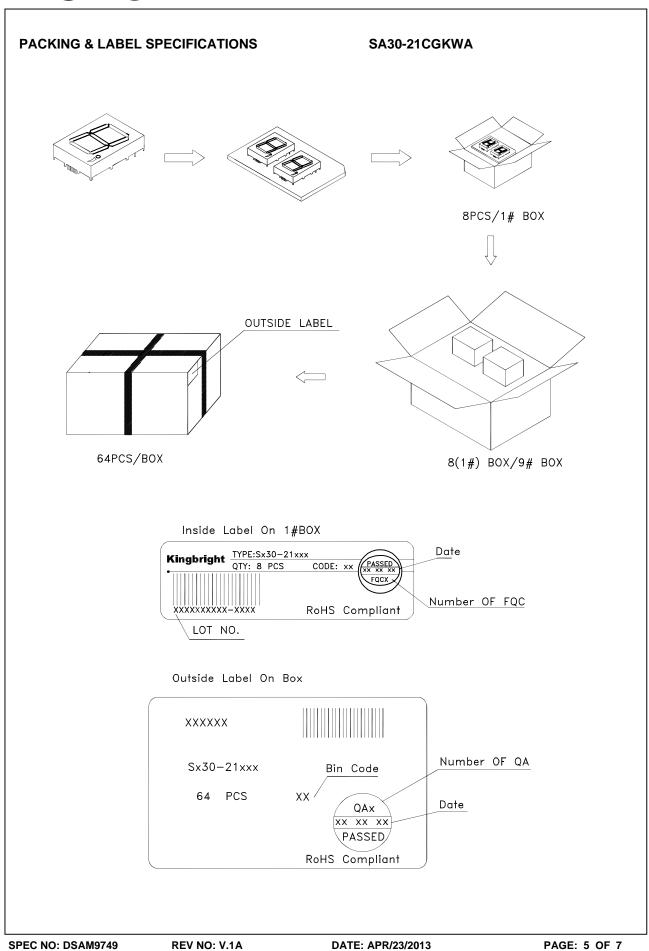








SPEC NO: DSAM9749 REV NO: V.1A DATE: APR/23/2013 PAGE: 4 OF 7
APPROVED: WYNEC CHECKED: Joe Lee DRAWN: F.Cui ERP: 1301003374



SPEC NO: DSAM9749 APPROVED: WYNEC

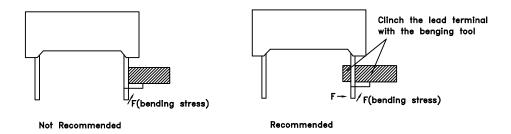
REV NO: V.1A CHECKED: Joe Lee DATE: APR/23/2013 DRAWN: F.Cui

PAGE: 5 OF 7 ERP: 1301003374

THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

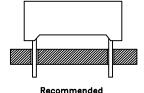
Do not bend the component leads by hand without proper tools. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



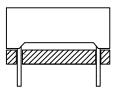
Installation

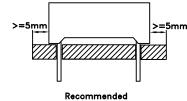
- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.





3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.





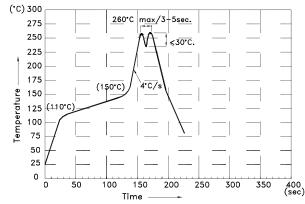
Not Recommended

SPEC NO: DSAM9749 REV NO: V.1A APPROVED: WYNEC CHECKED: Joe Lee

DATE: APR/23/2013 DRAWN: F.Cui PAGE: 6 OF 7 ERP: 1301003374

DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering , the PCB top-surface temperature should be kept below 105°C
- 5.No more than once.

Soldering General Notes:

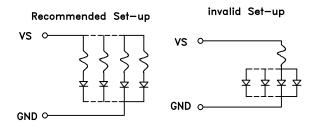
- 1. Through—hole displays are incompatible with reflow soldering.
- If components will undergo multiple soldering processes, or other processes
 where the components may be subjected to intense heat, please check with
 Kingbright for compatibility.

CLEANING

- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- 2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

- 1.Protective current—limiting resistors may be necessary to operate the Displays.
- 2.LEDs mounted in parallel should each be placed in series with its own current—limiting resistor.



PAGE: 7 OF 7

ERP: 1301003374

All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

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